

Your partner

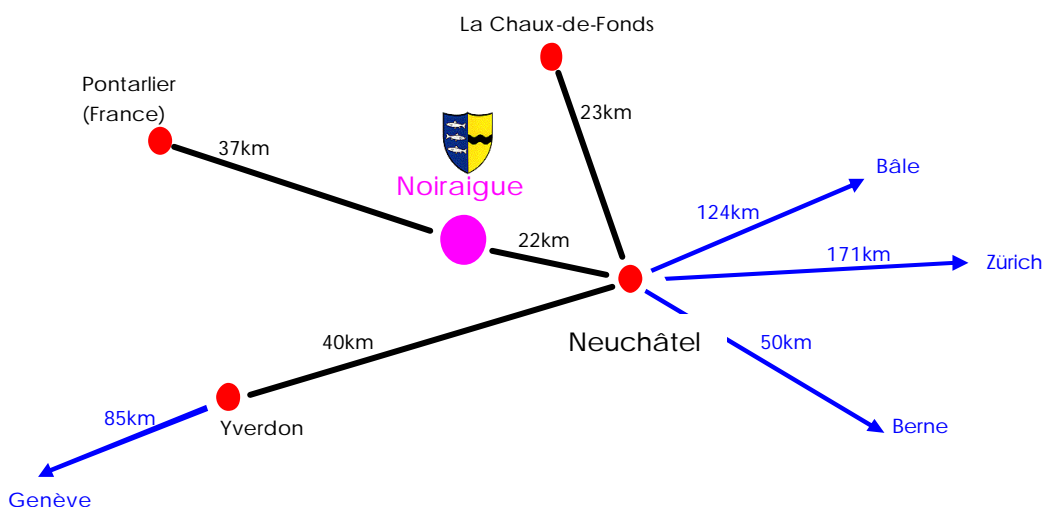
Since 1985, Microbonding SA has daily confirmed its technical know-how in the field of micro-electronics and packaging.

Microbonding SA is an independent company, having excellent relations with several microelectronics companies and universities; we form a well trained team together with own suppliers.

Microbonding SA offers you various services of subcontracting in micro-electronics and miniaturization, from the advice, the technical assistance to the development and to the manufacturing. Using a reactive and flexible structure, and knowing to adapt them to your needs, Microbonding SA is ready to provide you its services for prototypes, small series up to a large production. It is by assisting you in your most ambitious projects that Microbonding SA shows the extent of its experiment and is capable to present you the most adequate solutions for your products, in the best times.

Microbonding SA is active in the following domains: car, defense, telecom, industrial and consumer electronic, medical, watch industry...

Microbonding SA is located in Noiraigue, in the Val de Travers on the axis Neuchâtel - Pontarlier, around 20 km from Neuchâtel and 1hour 30 from Geneva or Zurich Airport.



Our services

Miniaturization and micro assembly require a continuous update of manufacturing processes, machines and hardware.

In order to be able to assist you in these fields and to enable you to remain competitive without major investments, Microbonding SA let you benefit from his acquired know-how and offers you the following services:

Development - conception

On the base of specifications of other document or starting from a simple idea of product, Microbonding SA proposes to its customers to undertake the project at any stage of advance with the constant concern to make a success of the technology transfer.

We propose you various possibilities of study and of realization according any substrate technology used (rigid printed circuit: double side, complex multi-layer with BGA, mixed, flexible, thick and thin film ceramic,..)

- The schematic design
- The design of the layout in accordance with the requirements of the various standards.
- The generation and the conversion of the data into the Gerber files for the manufacture of the substrates...

We also undertake the development of the product of the stage of prototype, until industrialization for the applications such as HF and BF, hybrid, numeric, analogic ...

Our experience in high density assembly, as well as the co-operation with our suppliers enable us to provide you designs which are perfectly adapted to your needs.

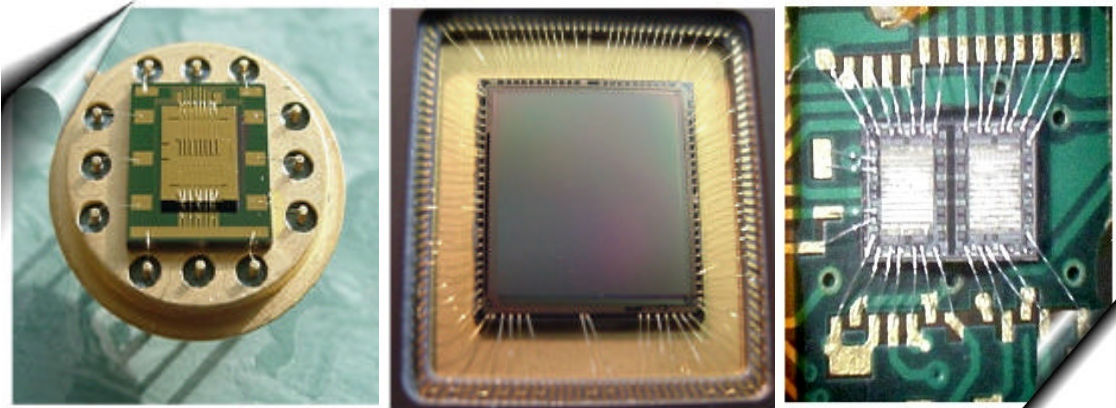
Fabrication – Test (From prototype to series)

In order to achieve a high miniaturization level with accessible costs and to make a success at the same time with an optimized manufacturing, we use state of the art technologies and machines, allowing assembly either in isolated parts, in multiples or from reel to reel.

We are also able to test the products with equipments designed in collaboration with our customer, or we will test only the assembly made in house.

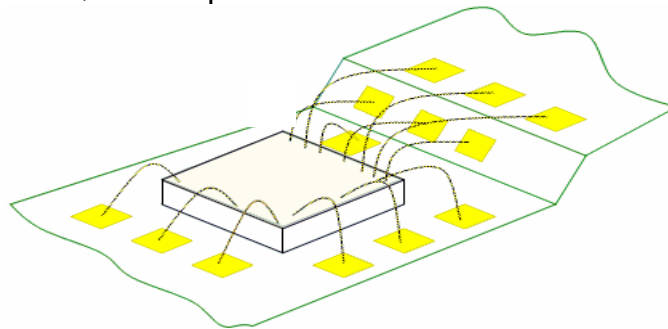
Our competences

Chip on Board (COB) Chip on Glass (COG)
Chip on Flex (COF) Chip on CHIP (COC)

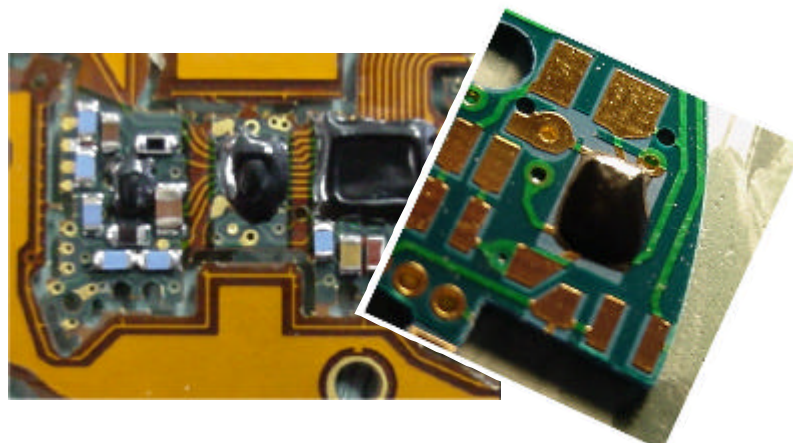


Microbonding SA is equipped for die mounting on rigid or flexible substrates, for all wire bonding from "Fine-Wire" to "Thick-Wire", "Au-Wedge-Wedge", "Al-Wedge-Wedge" and "Au-Ball Bonds"

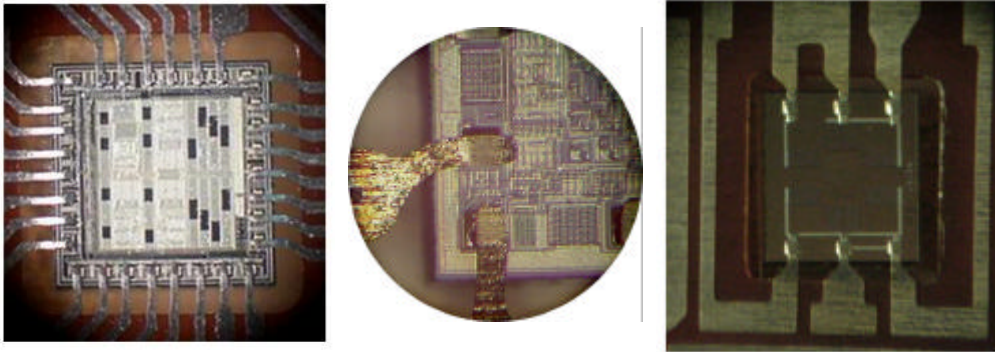
We can also bond in "2d", on nonparallel levels between them or in deep cavities.



Then, we make the coating with appropriate materials: epoxy, silicone, dielectric gel, UV Gloptop, ...



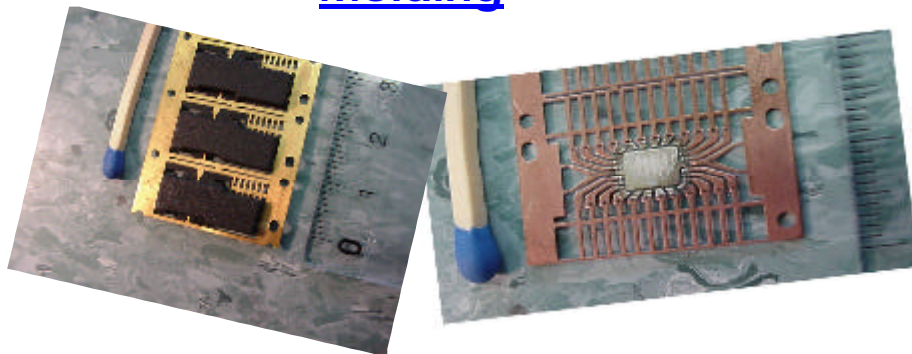
Tape Automated Bonding (TAB)



We mount in house the dice in the tape (Inner Lead Bonding), we process the manufactured tape (Outer Lead Bonding) and we perform the tape design in the standard formats (35mm, S8, etc.).

The Wafer-bumping and the Tape-manufacturing are executed by our subcontractors.

Molding

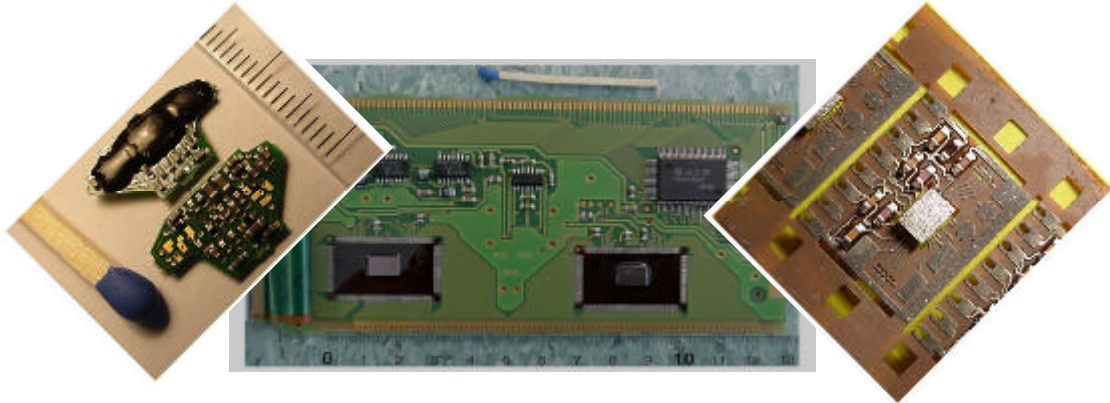


The rising demand of new packages and fast prototyping led us to the introduction of this last step in back-end operations at Microbonding SA. Indeed, we are able to offer you the molding of integrated circuits or hybrids in standard cases (DIL, SOIC etc.) or special developments according to your request. A sophisticated tool design allows the rapid introduction of new packages with a minimum of tooling cost and short lead-time.

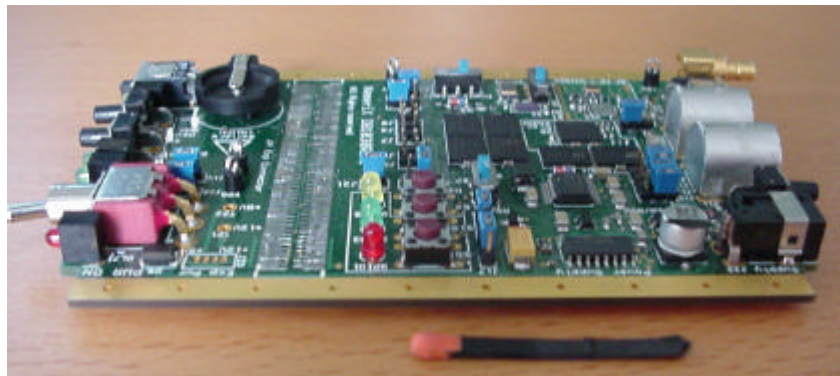
Due to the modularity of the molding cavities quantities ranging from prototypes to series production can be delivered.

In close cooperation with our partners we offer our support in the design and fabrication of lead frames adapted to your products and packages.

CMS BGA μ BGA CSP and traditional components

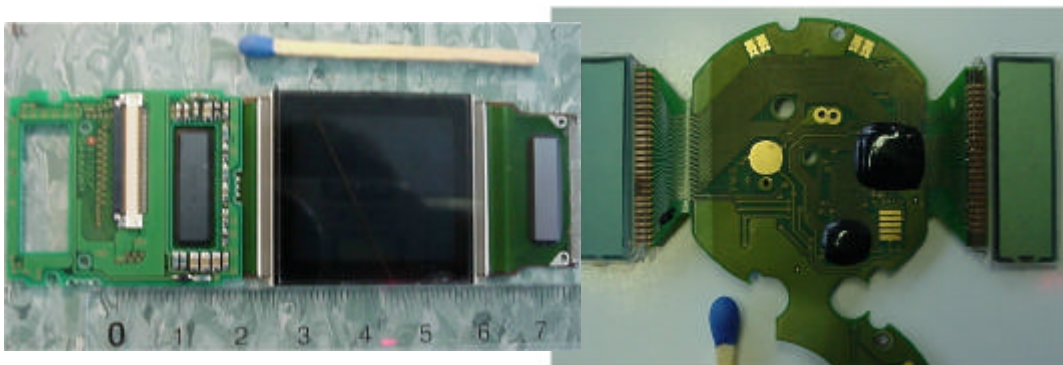


We offer high density assembly with all component sizes, either on single sided or double sided substrates, or in conjunction with other mounting technologies. A speciality is the SMT mounting from reel to reel.



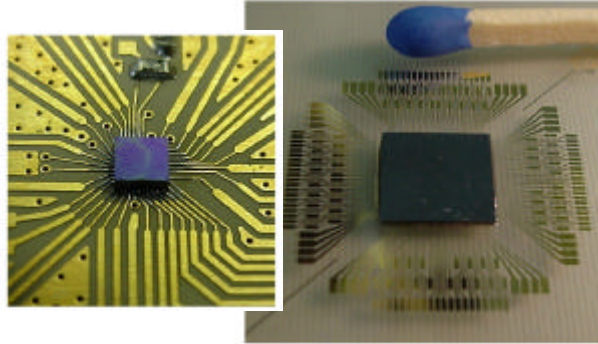
We also assemble the boards in traditional and mixed technology.

Heat sealing



Microbonding SA started an active development in heat sealing and ACF connection (Anisotropic Conductive Film) already in 1986 and the processing in 1993. Today, we are able to provide you services in these connecting technologies with various adhesives adapted to your needs.

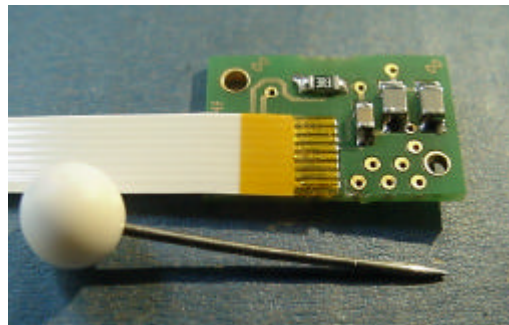
Flip Chip Bonding



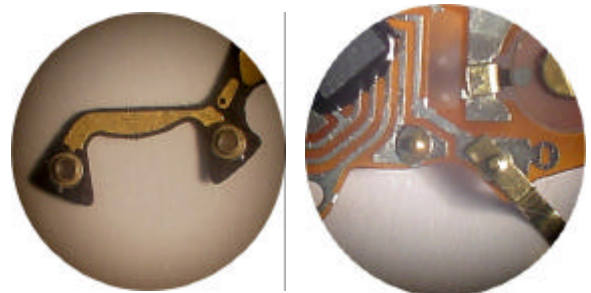
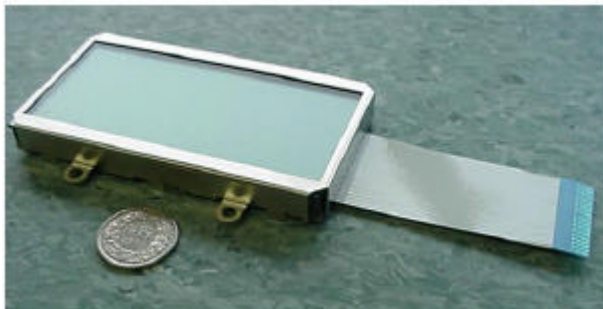
Microbonding SA can mount bumped devices on rigid or flexible substrates in flip chip technique and provides you with this novel high density mounting method.

HOT BAR Soldering

We perform also the welding of tablecloths, flexes or other products with the Hot Bar principle.



Mechanical parts and final assembly



We also complete your substrate with your mechanical parts (pins, supports...) by welding, riveting, thermo compression, ...

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